

EAST

| Ref # | Hits   | Search Query                                  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|--------|---|---|------------------|---------|------------------|
| S1    | 1      | "706389"                                      | US-PGPUB  | OR               | ON      | 2006/02/01 17:30 |
| S2    | 3891   | boat same (IC or (intergrated near2 circuit)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/02 16:59 |
| S3    | 458563 | adhesive and heat\$3                          | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 11:45 |
| S4    | 74     | S2 and S3                                     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 11:46 |
| S5    | 6      | Melvin near2 Alviar                           | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 11:46 |
| S6    | 1021   | 156/322                                       | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 14:34 |
| S7    | 13     | S6 and (IC or (intergrated near2 circuit))    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 14:15 |
| S8    | 2      | ("6077382"   "6722412").PN.                   | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | ON      | 2006/02/01 14:00 |
| S9    | 23     | S6 and (IC or (integrated near2 circuit))     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 14:23 |
| S10   | 4295   | boat same (IC or (integrated near2 circuit))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 14:16 |
| S11   | 458563 | adhesive and heat\$3                          | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2006/02/01 14:16 |

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| S12 | 110    | S10 and S11  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 14:16 |
| S13 | 3891   | boat same (IC or (intergrated<br>near2 circuit))   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 14:16 |
| S14 | 74     | S13 and S11  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 14:16 |
| S15 | 36     | S12 not S14  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 14:16 |
| S16 | 35     | S6 and semiconductor   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 14:34 |
| S17 | 75748  | (IC or (intergrated near2 circuit))<br>and (rail or tray or (wafer adj<br>cassette))             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 15:59 |
| S18 | 458563 | adhesive and heat\$3   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 15:59 |
| S19 | 3286   | S17 and S18  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 16:00 |
| S20 | 310    | "156"/\$.ccls. and S19   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/01 16:00 |
| S21 | 9      | ("5549716").URPN.  | USPAT   | OR | ON | 2006/02/01 16:27 |
| S22 | 7      | ("5173338"   "5547537"  <br>"5549716"   "6205745"  <br>"6291261"   "6560857"  <br>"6574857").PN. | US-PGPUB;<br>USPAT;<br>USOCR                          | OR | ON | 2006/02/01 16:35 |
| S23 | 3      | "268240"   | US-PGPUB  | OR | ON | 2006/02/02 16:59 |

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| S24 | 7     | yao-ting near2 huang   | US-PGPUB;<br>USPAT                                    | OR | ON | 2006/02/01 16:41 |
| S25 | 2     | "756307"   | US-PGPUB  | OR | ON | 2006/02/02 16:35 |
| S26 | 49    | "0045430"  | USPAT;<br>EPO; JPO;<br>DERWENT                        | OR | ON | 2006/02/01 18:15 |
| S27 | 2     | "200045430"  | USPAT;<br>EPO; JPO;<br>DERWENT                        | OR | ON | 2006/02/01 18:16 |
| S28 | 49    | "0045430"  | USPAT;<br>EPO; JPO;<br>DERWENT                        | OR | ON | 2006/02/01 18:17 |
| S29 | 71406 | carrier with substrate   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 10:55 |
| S30 | 551   | S29 same (IC or (intergrated<br>near2 circuit) or semicomductor)<br>and adhesive and heat\$3 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 10:56 |
| S31 | 363   | S30 and solder   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 11:44 |
| S32 | 57    | S30 and (solder near2 mask)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 13:10 |
| S33 | 0     | "438278"   | US-PGPUB  | OR | ON | 2006/02/02 11:44 |
| S34 | 71406 | carrier with substrate   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 15:09 |
| S35 | 551   | S34 same (IC or (intergrated<br>near2 circuit) or semicomductor)<br>and adhesive and heat\$3 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 15:10 |
| S36 | 242   | S35 and mask\$3  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 13:10 |

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| S37 | 14602   | (silver near2 (paste or glue or adhesive))                       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT           | OR | ON | 2006/02/02 14:38 |
| S38 | 395     | S37 same (IC or (intergrated near2 circuit))                     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 14:39 |
| S39 | 2514    | S37 same temperature   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 14:39 |
| S40 | 266     | S39 and (IC or (intergrated near2 circuit))                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 14:34 |
| S41 | 230     | (silver near2 (paste or glue or adhesive)) same (moisture)       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT           | OR | ON | 2006/02/02 14:38 |
| S42 | 58      | S41 same temperature   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 15:08 |
| S43 | 260     | carrier with (substrate same (heat\$3 with (moisture or water))) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:32 |
| S44 | 13      | S43 and (IC or (intergrated near2 circuit) or semicomductor)     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:32 |
| S45 | 1112632 | (IC or (intergrated near2 circuit))                              | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:03 |
| S46 | 0       | S45 same ((bond\$3 adj line) near3 test\$3)                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:00 |

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| S47 | 0       | S45 same ((bond\$3 adj line) near10 test\$3)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:00 |
| S48 | 7       | S45 and ((bond\$3 adj line) near10 measur\$6)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:04 |
| S49 | 4       | S45 and ((bond\$3 adj line) near10 (measurement or measuring or measure))                 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:31 |
| S50 | 1577128 | (IC or (integrated near2 circuit))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:03 |
| S51 | 11      | S50 and ((bond\$3 adj line) near10 measur\$6)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:04 |
| S52 | 8       | S50 and ((bond\$3 adj line) near10 (measurement or measuring or measure))                 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:43 |
| S53 | 11      | S50 and ((bond\$3 adj line) near10 (measurement or measuring or measure or test\$3))      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:53 |
| S54 | 185     | S50 and ((bond\$3 adj line) near10 thick\$4)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:34 |
| S55 | 1       | (S50 and ((bond\$3 adj line) near10 thick\$4)) same (measuring or measurement or measure) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:34 |
| S56 | 7713    | S50 and (bond\$3 near10 (measurement or measuring or measure or test\$3))                 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:53 |

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| S57 | 1046    | S50 and ((bond\$3 near10 (measurement or measuring or measure or test\$3)) same thick\$4)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/02 17:54 |
| S58 | 279     | S50 and ((bond\$3 near10 (measurement or measuring or measure or test\$3)) with thick\$4)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:17 |
| S59 | 1577128 | (IC or (integrated near2 circuit))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:17 |
| S60 | 155     | S59 and ((bond\$3 with (measurement or measuring or measure or test\$3)) near10 thick\$4)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:17 |
| S61 | 524     | carrier with (substrate same (heat\$3 with (moisture or water or evaporat\$4)))   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:32 |
| S62 | 26      | S61 and (IC or (intergrated near2 circuit) or semicomductor)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:36 |
| S63 | 7       | ("5173338"   "5547537"   "5549716"   "6205745"   "6291261"   "6560857"   "6574857").PN.   | US-PGPUB;<br>USPAT;<br>USOCR                          | OR | ON | 2006/02/03 09:55 |
| S64 | 0       | S63 and (moisture or water)   | US-PGPUB;<br>USPAT;<br>USOCR                          | OR | ON | 2006/02/03 09:34 |
| S65 | 489     | ((pre-heat\$3 or preheat\$3) with (cassette or tray or boat or rail or carrier)) and (IC or (intergrated near2 circuit) or semicomductor)                   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:37 |
| S66 | 355     | ((pre-heat\$3 or preheat\$3) with (cassette or tray or boat or rail or carrier)) same temperature) and (IC or (intergrated near2 circuit) or semicomductor) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT | OR | ON | 2006/02/03 09:37 |
| S67 | 1       | S63 and heat\$3   | US-PGPUB;<br>USPAT;<br>USOCR                          | OR | ON | 2006/02/03 09:56 |

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| S68 | 1 | S63 and \$3heat\$3 | US-PGPUB;<br>USPAT;<br>USOCR | OR | ON | 2006/02/03 09:56 |
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